# **MA2J113** (MA113)

### Silicon epitaxial planar type

#### For switching circuits

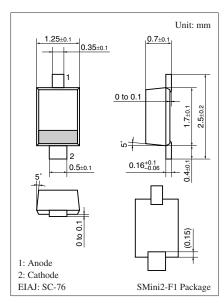
#### ■ Features

- Allowing high-density mounting
- Ensuring the forward current (Average) capacity  $I_{F(AV)} = 200 \text{ mA}$
- High breakdown voltage:  $V_R = 80 \text{ V}$

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Maximum peak reverse voltage	$V_{RM}$	80	V
Forward current (Average)	I <sub>F(AV)</sub>	200	mA
Peak forward current	$I_{FM}$	600	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C





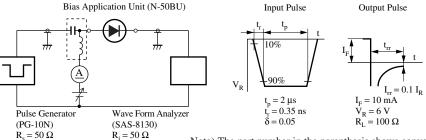
Marking Symbol: 1D

#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 200 \text{ mA}$			1.1	V
Reverse current	$I_{R1}$	V <sub>R</sub> = 15 V			50	nA
	$I_{R2}$	V <sub>R</sub> = 75 V			500	
	$I_{R3}$	$V_R = 75 \text{ V}, T_a = 100^{\circ}\text{C}$			100	μΑ
Terminal capacitance	Ct	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$			4	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
		$I_{rr} = 0.1 I_R$ , $R_L = 100 \Omega$				

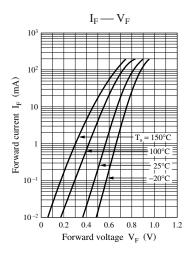
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

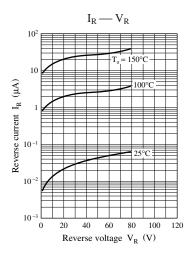
- 2. Absolute frequency of input and output is 100 MHz.
- 3. \*: t<sub>rr</sub> measurement circuit

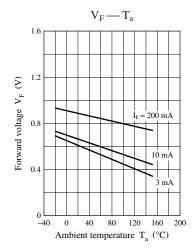


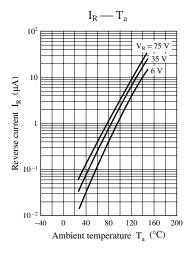
Note) The part number in the parenthesis shows conventional part number.

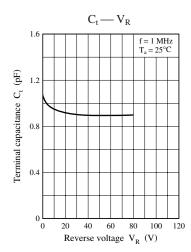
### **Panasonic**

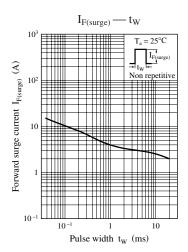












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